

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2914hdhc-1#trpbf

(Engineering Calculation)

DFN 5mm X 3mm Exp. Pad

(printed on: 2020-07-11 16:20:41)

**TOTAL MASS (g) : 0.038452**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001279	1000000	33262.25		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.017069	974800.0625	443904.09375		
		Iron (Fe)	7439-89-6	0.000411	23500	10688.6503906		
		Phosphorus (P)	7723-14-0	0.000015	850	390.096740723		
		Zinc (Zn)	7440-66-6	0.000015	850	390.096740723		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.017510</b>	<b>1000000</b>	<b>455372.96875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000817	1000000	21247.3242188		
		<b>External Plating Total:</b>				<b>0.000817</b>	<b>1000000</b>	<b>21247.3242188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000391	1000000	10168.5224609		
		<b>Internal Plating Total:</b>				<b>0.000391</b>	<b>1000000</b>	<b>10168.5224609</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000676	750000	17580.359375		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000225	250000	5851.45117188		
<b>Die Attach Total:</b>				<b>0.000901</b>	<b>1000000</b>	<b>23431.8105469</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.002274	130000	59138.671875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.015041	860000	391163.03125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000175	10000	4551.12841797		
		<b>Encapsulation Total:</b>				<b>0.017490</b>	<b>1000000</b>	<b>454852.78125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000064	1000000	1664.4128418		
					<b>TOTAL MASS (g) :</b>	<b>0.038452</b>		